

Prof. Yuan Yang

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President of International Engineering College of XUT, Member of China Power Supply Society, Member of China Electro Technical Society, Member of Chinese Society of Academic Degrees and Graduate Education.



Education Background

- BE, Applied Electronic Technology, Xi'an University of Technology, 1997.
- ME, Micro-Electronics and Solid Electronics, Xi'an University of Technology, 2000.
- Ph.D, Micro-Electronics and Solid Electronics, Xi'an University of Technology, 2004,
- Visiting Scholar, Kyushu University, 2004.

Research Field

- Integrated Circuit Design
- Low Power Management
- Embedded System Design

Academic achievements

1. Wei Yang, Wei Xiang, Yuan Yang, Peng Cheng, Optimizing federated learning with deep reinforcement learning for digital twin empowered industrial IoT. *IEEE Transactions on Industrial Informatics*, vol.19(2), pp. 1884-1893, 2023.
2. Yuan Yang, Yang Wen, Yong Gao. A novel active gate driver for improving switching performance of high-power SiC MOSFET modules. *IEEE Transactions on Power Electronics*, vol. 34(8), pp. 7775-7787, 2019.
3. Yang Wen, Yuan Yang, Yong Gao. Active gate driver for improving current sharing performance of paralleled high-power SiC MOSFET modules. *IEEE Transactions on Power Electronics*, vol. 36(2), pp. 1491-1505, 2021.
4. Fengjuan Wang, Kai Zhang, Xiangkun Yin, Ningmei Yu, Yuan Yang. A miniaturized wideband interdigital bandpass filter with high out-band suppression based on TSV technology for W-band application. *IEEE Transactions on Very Large Scale Integration Systems*. Vol. 30(7), pp. 989-992, 2022.
5. Tong Zhang, Lisha Yan, Yuan Yang, Trust Evaluation Method for Clustered Wireless Sensor Networks based on Cloud Model, *Wireless Networks*, Vol.24, No.3, pp.777-797, 2018.
6. Haohao Ma, Yuan Yang, Lei Wu, Yang Wen, Qiang Li. Review of the designs in low inductance SiC half-bridge packaging. *IET Power Electronics*, vol. 15(11), pp. 989-1003, 2022.